Lead Free

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# **SPECIFICATIONS**

Approved by

Messrs.

Product	CRYSTAL UNIT				
Type of Holder	CFS-206				
Nominal Frequency	32.768 kHz				
Customer's Parts Number					
CITIZEN Parts Number					

Sales

CITIZEN WATCH Co.,LTD Crystal Device Division.

6-1-12, Tanashi-cho, Nishitokyo-shi, Tokyo, 188-8511, JAPAN

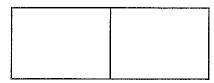
TEL:81-424-67-6214 FAX:81-424-67-8503

Manufacturer

MIYOTA Co.,LTD. Crystal Device Division.

4107-5, Miyota, Miyota-machi, Kitasaku-gun, Nagano, 389-0294, JAPAN

TEL:81-267-32-3331 FAX:81-267-32-4960



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#### 1. Scope

This document contains specifications for the crystal unit to be supplied by MIYOTA Co ,LTD

1.1 If something defined ambiguously or undefined in document happened, the customer and MIYOTA would discuss and take necessary steps by mutual consent

- 1.2 Product test data can't be attached to this document.
- 1.3 This product is not authorized for use as a critical component in life support devices or systems.

### 2. Electrical Specifications

2.1 Nominal Frequency 32.768 kHz

2.2 Operating Temperature Range -20 to +70 degC

2.3 Storage Temperature Range -40 to +85 degC

2.4 Frequency Tolerance +/- 20ppm Max. at 25 degC

2.5 Frequency Tolerance over Turnover Temp.; 25 +/- 5degC

Operating Temperature Range Temp. Coefficient: -0.034 +/- 0.006ppm / degC<sup>2</sup>

2.6 Equivalent Series Resistance 35k ohm Max. at 25 degC

2.7 Insulation Resistance 500M ohm Min/DC100V +/- 15V

#### 3. Test Conditions

3.1 Load Capacitance 12.5 pF

This Load Capacitance has been fixed on customer's

request

3.2 Level of Drive MAX.1 Micro W

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## 4. Mechanical and Environmental Tests

Test Name		Test Conditions					
1.N	lechanical Tests						
1-1	Shock	hock Drop 3 times from the height of 75 cm onto hard wooden board with thickness of 3 cm					
1-2	Vibration	Vibration Frequency: 10~500 Hz, 1.5mm, full wave, or acceleration 10G,  Cycle: 1 5 minutes, Direction: X Y.Z  Time: 2 hours in each direction, for 6 hours in total.					
1-3	Lead Pull	Weight: 1.0kg, Time: 30 +/- 5 seconds	A·C				
1-4	Bending Strength	Weight: 0.5kg, Bending Angle: 90 degrees, Bending Count: 2 times	A·C				
1-5	Solderability  After applying RMA flux, dip in solder. Dipping Time: 5 +/- 0 5 seconds.  Soldering Temperature: 230 +/- 5 degC.  Dipping Depth: 2 mm from the edge of terminals of samples.						
1-6	Resistance to Soldering Heat	Dip in solder. Dipping Time: 10 +/- 0.5 seconds.  Soldering Temperature: 260 +/- 5 degC.  Dipping Depth: 2mm from the edge of lead-wires of samples	В				
1-7	Sealing Tightness	Leak rate shall be measured by using Helium Leak Detector	E				
2.E	nvironmental Test	S					
2-1	Storage In Low Temperature	Expose the sample in an inoperative mode to 240 hours at -40 degC.	A				
2-2	Storage In High Temperature	Expose the sample in an inoperative mode to 240 hours at +85 degC.	В				
2-3	Humidity	Expose the sample in an inoperative mode to 240 hours at +65 degC, and 95%RH	В				
2-4	Thermal Shock	Subject the sample to 5 temperature variation cycles at -40 degC for 30 minutes and +100 degC for the next 30 minutes in each cycle.	A				

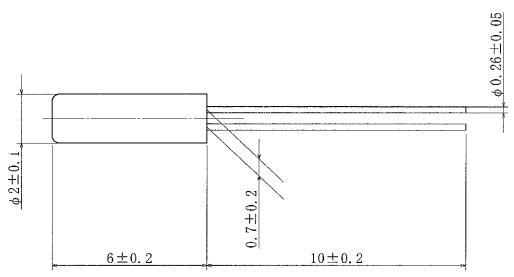
Cri	iteria	
Criteria No.	Criteria	
A.	Any variation between the pre- and post-test frequencies shall remain within +/- 5ppm. The equivalent series resistance shall remain within its specified tolerance range after the post-test.	Load Iool
В	Any variation between the pre- and post-test frequencies shall remain within +/- 10ppm. The equivalent series resistance shall remain within its specified tolerance range, after the post-test.	0.5R
С	After each test, no visible damage, nor the hermetic seal break down.	
D	At least 90% of each dipped area shall be covered by fresh solder.	<u>1.5</u> mm
E	1×10 <sup>-2</sup> Micro Pa m <sup>3</sup> /s Max.	Fig 1

<sup>\*</sup> Measurements should be taken place at 25 +/- 2 degC after each test, the samples shall left at 25 degC for one to two hours.

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## 5. Dimensions





## 6. Marking Standards

Sym1

Table 1

Table 1										
Month	1	2		9	10	11	12			
Code	1	2		9	X	Y	Z			

S,1: Manufacture's ID Code

y: The last digit of production year.

m: Production month (See Table 1)

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## 7. Packing

Packing method is taken precautions to prevent damage due to transportation and handling.

#### 8. Manufacturer

(Domestic) MIYOTA CO.,LTD

4107-5, Miyota, Miyota-machi, Kitasaku-gun, Nagano, 389-0294, JAPAN

Tel:0267-32-3331

(Oversea) MASIER CROWN ELECTRONICS CO ,LTD.

No.3 BLDG,137,XINXING EN

ROAD, WUZHOU, GUANGXI, CHINA.

TEL:774-3863148

### 9. Ozone Depleting Substance (ODS)

This Product doesn't use the class I ODS at any of production processes, and component parts

<sup>\*</sup> This manufacture is under the control of MIYOTA CO, LTD